

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Switch-mode Power Rectifier

DPAK Surface Mount Package

These state-of-the-art devices are designed for use in switching power supplies, inverters and as free wheeling diodes.

Features

- Ultrafast 35 Nanosecond Recovery Time
- Low Forward Voltage Drop
- Low Leakage
- ESD Rating:
 - Human Body Model = 3B (> 8 kV)
 - ◆ Machine Model = C (> 400 V)
- NRVUD, SRVUD and SNRVUD Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds



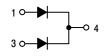
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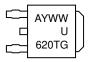
ULTRAFAST RECTIFIER 6.0 AMPERES 200 VOLTS



DPAK CASE 369C



MARKING DIAGRAMS





A = Assembly Location

/ = Year

WW = Work Week

U620T = Device Code (MURD/NRVUD/

SNRVUD620CT)

US620T = Device Code (SRVUD620CT)

= Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
MURD620CTG	DPAK (Pb-Free)	75 Units / Rail
NRVUD620CTG	DPAK (Pb-Free)	75 Units / Rail
MURD620CTT4G	DPAK (Pb-Free)	2,500 / Tape & Reel
NRVUD620CTT4G	DPAK (Pb-Free)	2,500 / Tape & Reel
SRVUD620CTT4G	DPAK (Pb-Free)	2,500 / Tape & Reel
SNRVUD620CTT4G	DPAK (Pb-Free)	2,500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	200	V
Average Rectified Forward Current (Rated V _R , T _C = 140°C) Per Diode Per Device	l _{F(AV)}	3.0 6.0	А
Peak Repetitive Forward Current (Rated V _R , Square Wave, 20 kHz, T _C = 145°C) Per Diode	IF	6.0	А
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, 60 Hz)	I _{FSM}	50	Α
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-65 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS (Per Diode)

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	9	°C/W
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{ heta JA}$	80	°C/W

^{1.} Rating applies when surface mounted on the minimum pad sizes recommended.

ELECTRICAL CHARACTERISTICS (Per Diode)

Characteristic	Symbol	Value	Unit
$\label{eq:maximum Instantaneous Forward Voltage Drop (Note 2)} \begin{tabular}{l} (i_F = 3 \text{ Amps, } T_C = 25^\circ \text{C}) \\ (i_F = 3 \text{ Amps, } T_C = 125^\circ \text{C}) \\ (i_F = 6 \text{ Amps, } T_C = 25^\circ \text{C}) \\ (i_F = 6 \text{ Amps, } T_C = 125^\circ \text{C}) \\ \end{tabular}$	VF	1 0.96 1.2 1.13	V
Maximum Instantaneous Reverse Current (Note 2) (T _J = 25°C, Rated dc Voltage) (T _J = 125°C, Rated dc Voltage)	i _R	5 250	μΑ
Maximum Reverse Recovery Time (I _F = 1 Amp, di/dt = 50 Amps/ μ s, V _R = 30 V, T _J = 25°C) (I _F = 0.5 Amp, i _R = 1 Amp, I _{REC} = 0.25 A, V _R = 30 V, T _J = 25°C)	t _{rr}	35 25	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 2. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.

TYPICAL CHARACTERISTICS

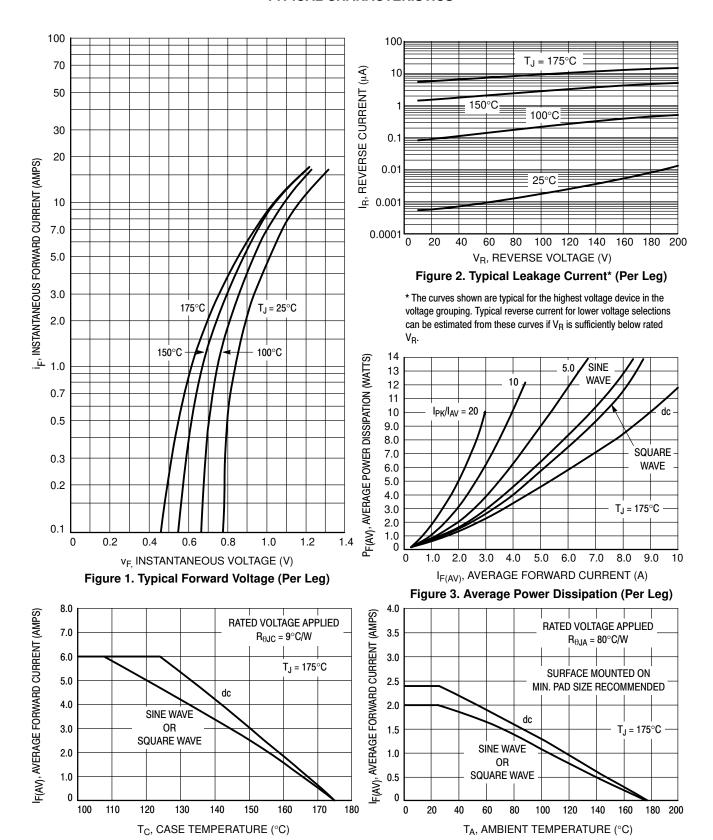


Figure 4. Current Derating, Case (Per Leg)

TYPICAL CHARACTERISTICS

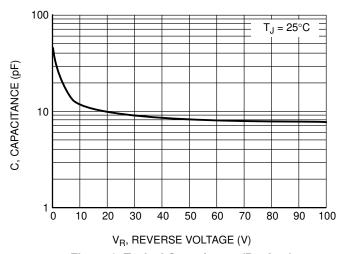
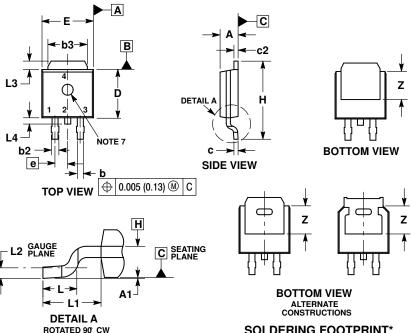


Figure 6. Typical Capacitance (Per Leg)

PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE)

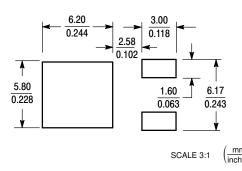
CASE 369C ISSUE F



- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: INCHES.
 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-
- MENSIONS b3, L3 and Z.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE
- 5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
 6. DATUMS A AND B ARE DETERMINED AT DATUM DI ANE LE
- 7. OPTIONAL MOLD FEATURE.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
С	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
е	0.090	BSC	2.29	BSC
Н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114	REF	2.90	REF
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Z	0.155		3.93	

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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